RELIABILITY REPORT

FOR

MAX9312ECJ+
(MAX9314)

PLASTIC ENCAPSULATED DEVICES

November 13, 2008

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

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Conclusion

The MAX9312ECJ+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

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I. Device Description

A. General

The MAX9312/MAX9314 are low skew, dual 1-to-5 differential drivers designed for clock and data distribution. These devices accept two inputs. Each input is reproduced at five differential outputs. The differential inputs can be adapted to accept single-ended inputs by connecting the on-chip VBB supply to one input as a reference voltage. The MAX9312/MAX9314 feature low part-to-part skew (30ps) and output-to-output skew (12ps), making them ideal for clock and data distribution across a backplane or a board. For interfacing to differential HSTL and LVPECL signals, these devices operate over a +2.25V to +3.8V supply range, allowing high-performance clock or data distribution in systems with a nominal +2.5V or +3.3V supply. For differential LVECL operation, these devices operate from a -2.25V to -3.8V supply. The MAX9312 features an on-chip VBB reference output of 1.425V below the positive supply voltage. The MAX9314 offers an on-chip VBB reference output of 1.32V below the positive supply voltage. Both devices are offered in space-saving, 32-pin 5mm x 5mm TQFP, 5mm x 5mm QFN, and industry-standard 32-pin 7mm x 7mm TQFP packages.

II. Manufacturing Information

A. Description/Function:	Dual 1:5 Differential LVPECL/LVECL/HSTL Clock and Data Drivers
B. Process:	GST2
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	ATK Korea; Carsem Malaysia
F. Date of Initial Production:	July 28, 2001

III. Packaging Information

A. Package Type:	32-pin LQFP
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Gold (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-3601-0002
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
L. Multi Layer Theta Ja:	48.4°C/W
M. Multi Layer Theta Jc:	12°C/W

IV. Die Information

A. Dimensions:	69 X 69 mils
B. Passivation:	Si_3N_4 (Silicon nitride)
C. Interconnect:	Poly / Au
D. Backside Metallization:	None
E. Minimum Metal Width:	2 microns (as drawn)
F. Minimum Metal Spacing:	2 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 150°C biased (static) life test are pending. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 48 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.4 \times 10^{-9}$

$\lambda = 22.4$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the GST3 Process results in a FIT Rate of 1.0 @ 25C and 17.8 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The EC03-1 die type has been found to have all pins able to withstand a HBM transient pulse of +/-3000 V per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of 250 mA.

Table 1
Reliability Evaluation Test Results

MAX9312ECJ+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 150°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data